

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

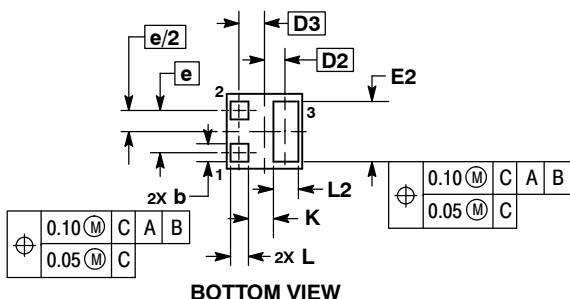
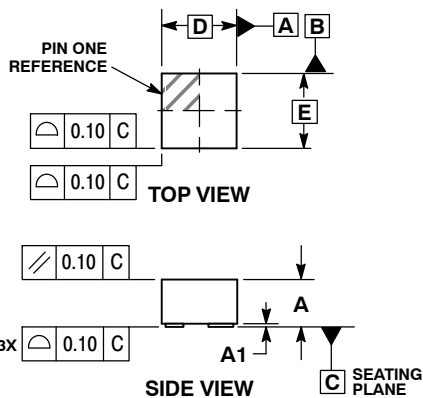
ON Semiconductor®



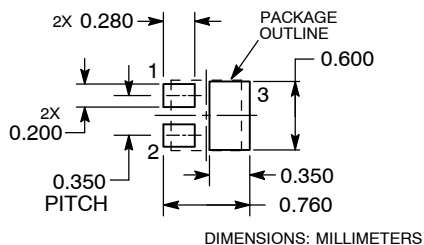
SCALE 8:1

XLLGA3, 0.62x0.62, 0.35P
CASE 713AB
ISSUE O

DATE 25 SEP 2012



RECOMMENDED SOLDER FOOTPRINT*



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.

MILLIMETERS		
DIM	MIN	MAX
A	0.340	0.440
A1	0.000	0.030
b	0.100	0.200
D	0.620	BSC
D2	0.175	BSC
D3	0.205	BSC
E	0.620	BSC
E2	0.400	0.600
e	0.350	BSC
K	0.200	REF
L	0.090	0.210
L2	0.110	0.310

GENERIC MARKING DIAGRAM*



X = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON84074E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	XLLGA3, 0.62X0.62, 0.35P	PAGE 1 OF 2

